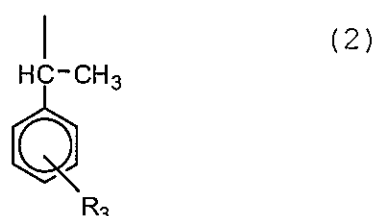
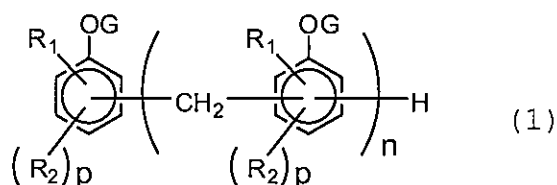


Abstract

Provided is an epoxy resin composition that shows excellent low dielectric property, exhibits excellent flame retardancy in the absence of a halogen, and is useful in, for example, a laminated material, a semiconductor-sealing material, a molding material, a powder coating, and an adhesive material. The epoxy resin composition contains, as epoxy resin components, a styrene-modified epoxy resin represented by the following general formula (1) and a phosphorus-containing epoxy resin having a phosphorus content of from 1.0 to 5.0 wt%, and the content of the epoxy resin represented by the general formula (1) is 30 wt% or more with respect to the entirety of the epoxy resins:



(wherein G represents a glycidyl group, R₁ and R₃ each represent hydrogen or a hydrocarbon group, R₂ represents a substituent represented by the formula (a), n represents a number of from 1 to 20, and p represents a number of from 0.1 to 2.5).